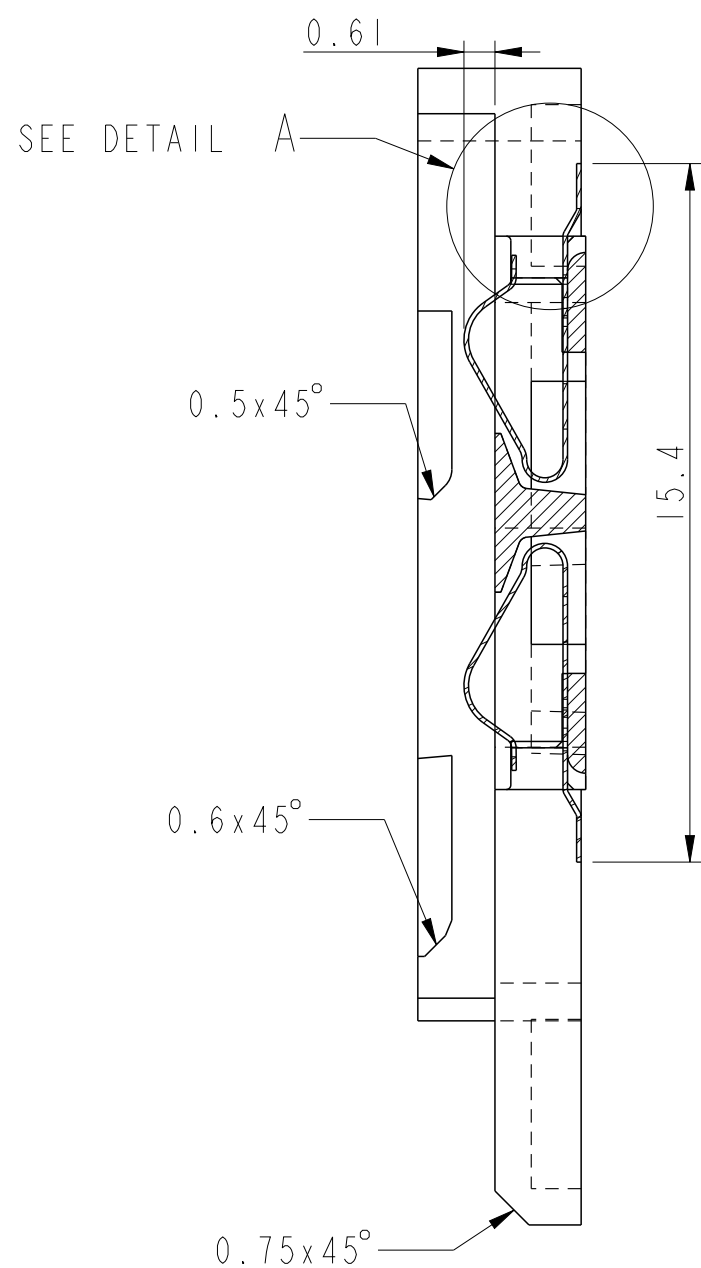
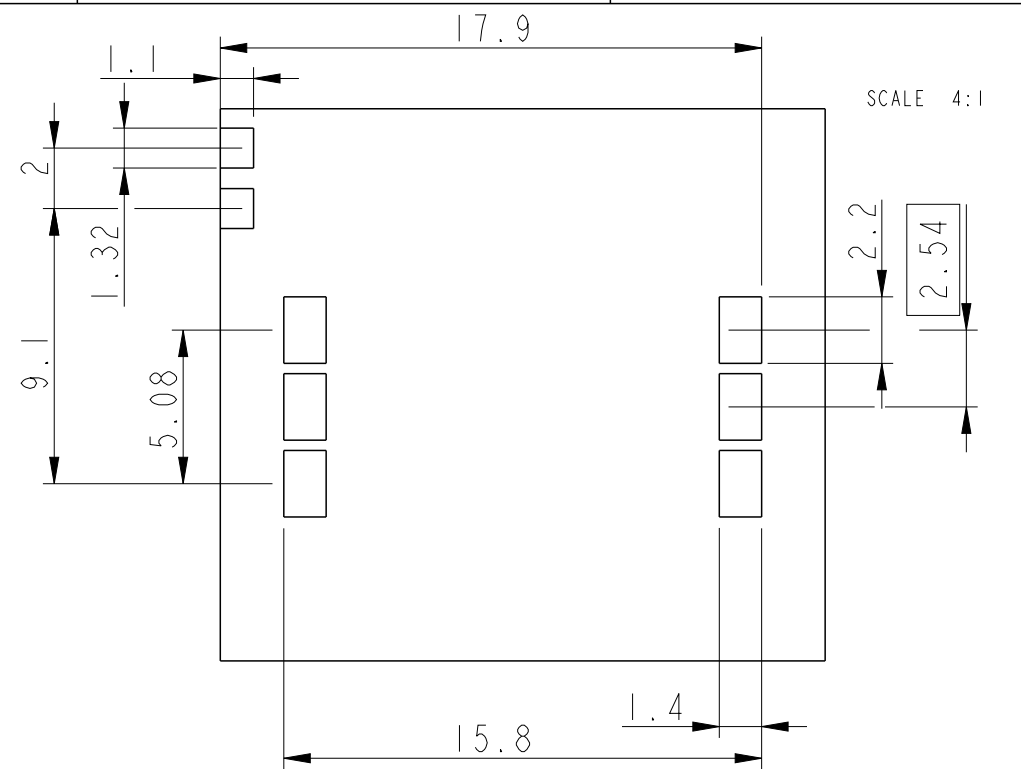
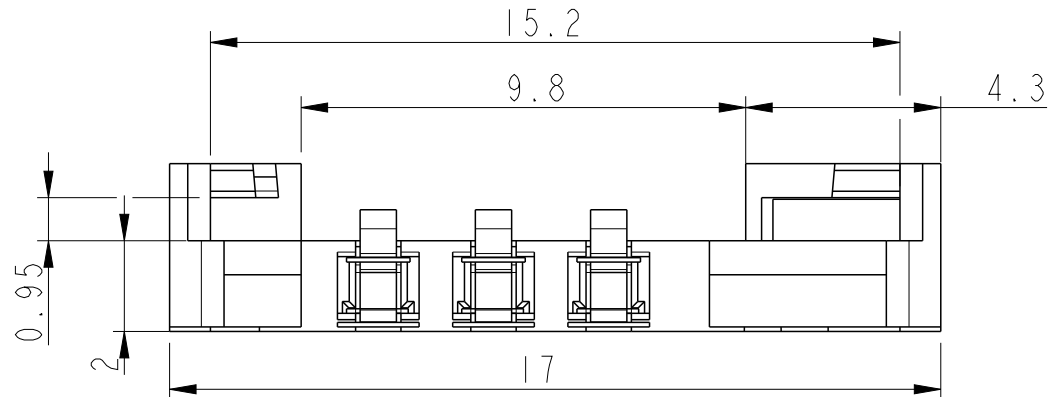
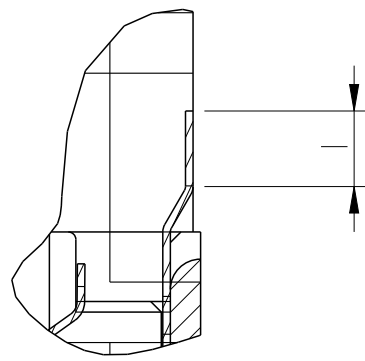
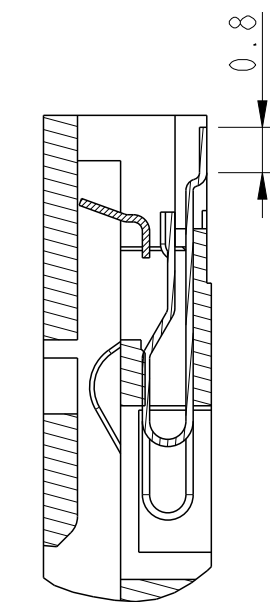
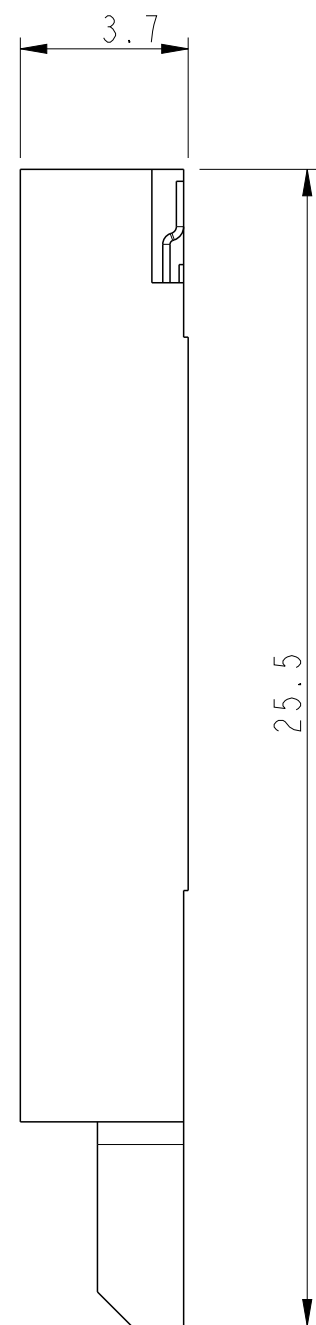
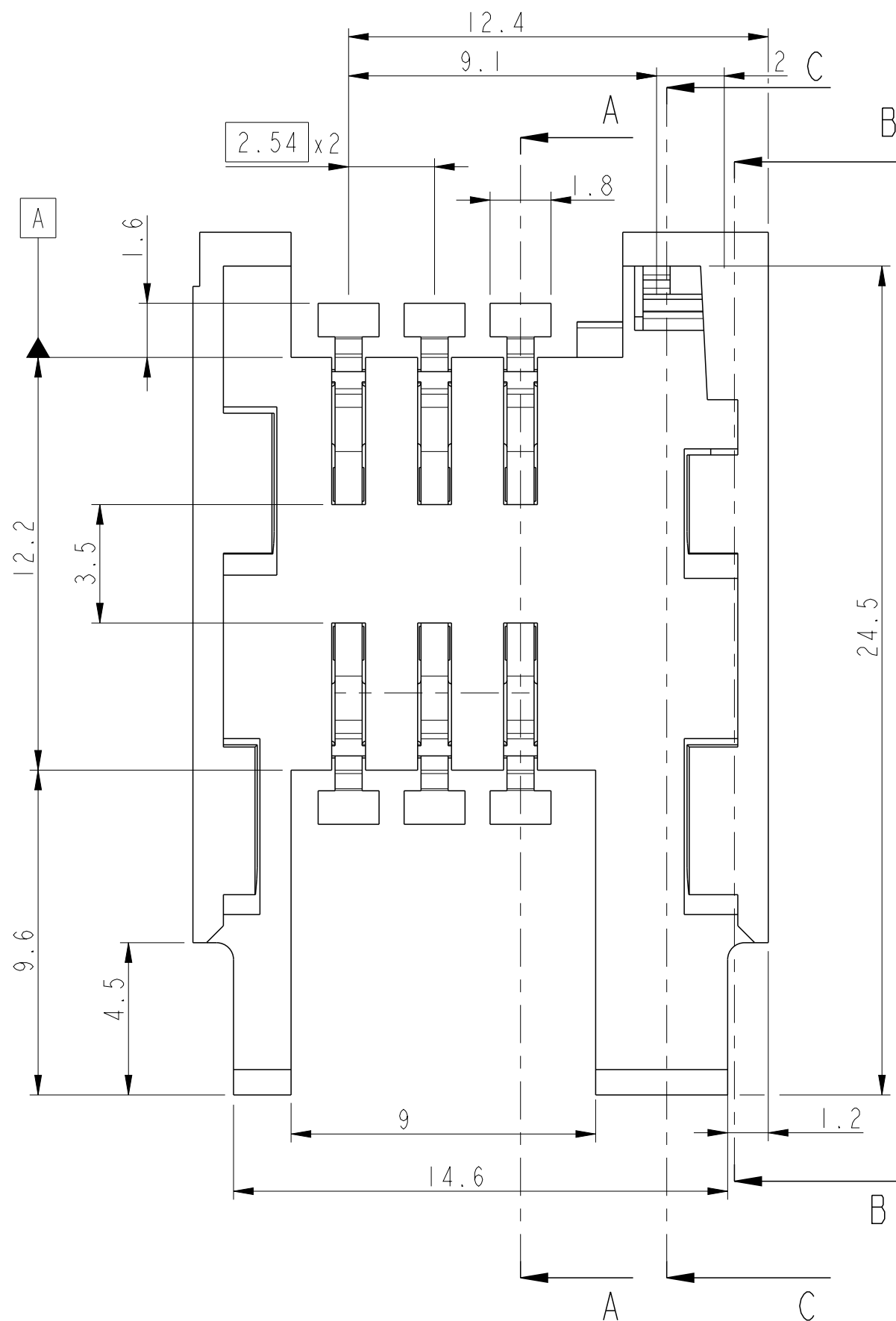


PART NUMBER
LEAD FREE VERSION
7111SI615A02LF

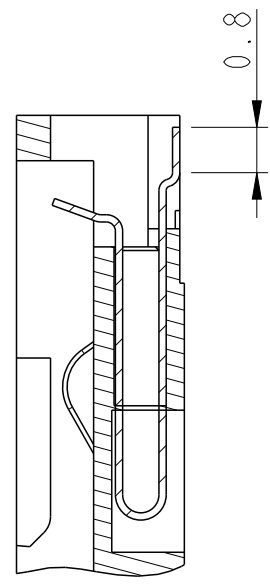
DETAIL A
SCALE 10:1



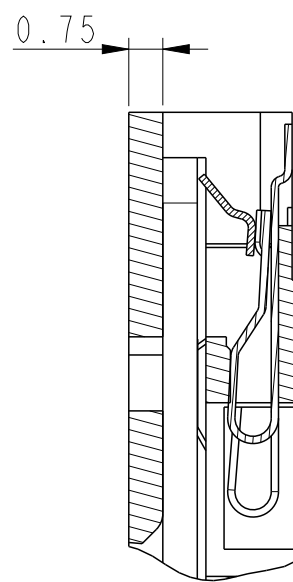
SECTION A-A



SECTION B-B



SECTION C-C



SECTION B-B
SCALE 6:1

DETAIL OF SWITCH

LEAD FREE VERSION:

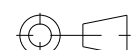
"This product meets European Union Directives and other country regulations as described in GS-22-008"

The housing will withstand exposure to 260°C peak temperature for 10 seconds in a convection reflow oven.

PROCESSING

Ni 2 µm
Gold 2.5 µm/Equivalent PdNi over Ni on contact area
Solder tail: Matte tin 2.5 µm (for lead free version)

GENERAL TOLERANCES:±0.1

www.fciconnect.com			surface - 		tolerance std ISO 1302 ISO 406 ISO 1101		projection 		mm 				
			TOLERANCES UNLESS OTHERWISE SPECIFIED										
Dr	BERNARDET	1998/09/02	ANGULAR	LINEAR	0.X		size		Scale				
Eng	ODIC	1998/09/02			0.XX		A2		6:1				
Chr	DILIP THOMAS	2006/07/18			0.XXX		ECN		109-0291				
Appr	K.V.SIVADAS	2006/07/18	0° ±°		±								
			Product family				MOBILE IO		Spec ref --				
			title				SIMCARD CONNECTOR WITH SWITCH				Rev.		
			TYPE SI6				VJW_54479				F		
			catalog no				SEE NOTES				CUSTOMER		
							sheet 1 of 1						

rev	ecn no	dr	date
01	-	JBB	1998-09-02
A	-	-	2001-12-06
B	-	MPE	2002-03-06
C	LS2025	MPE	2002-05-04
D	I05-0167	NT	2005/09/23
E	I06-0121	DTK	2006/07/18
F	I09-0291	RPK	2009/12/30

PDM: Rev:F

STATUSReleased8 Printed: Oct 06, 2010